

HIGH-DENSITY MULTICHIP MODULE PACKAGE

The invention discloses a high-density multi-chip module package which can integrates active and passive devices stacked by a three-dimensional face-to-back interconnection. The multichip module package of the invention at least comprises a multichip module substrate which has an semiconductor substrate, an insulating layer on the semiconductor substrate, a multilayer interconnection structure on the insulating layer, and a plurality of conductive plugs penetrating the semiconductor substrate and the insulating layer to provide electric connection with the multilayer interconnection structure; and a plurality of chips disposing on the semiconductor substrate and electrically connecting to the multilayer interconnection structure through the conductive plugs.

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